

L Number	Hits	Search Text	DB	Time stamp
1	36801	(semiconductor or substrate or wafer)with (ball or roller)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:19
2	9536	((semiconductor or substrate or wafer)with (ball or roller)) and support	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:15
3	5366	(semiconductor or substrate or wafer) with ((ball or roller) and support)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:16
4	3564	((semiconductor or substrate or wafer) with ((ball or roller) and support)) not solder	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:17
5	913	((semiconductor or substrate or wafer) with ((ball or roller) and support)) not solder and chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:18
6	835	((semiconductor or substrate or wafer) with ((ball or roller) and support)) not solder) and chamber) and (coat\$3 or plat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:19
7	2803	(semiconductor or substrate or wafer) with ((ball or roller) ADJ3 (coat\$3 or plat\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:21
8	2488	((semiconductor or substrate or wafer) with ((ball or roller) ADJ3 (coat\$3 or plat\$3))) not solder	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:22
9	21	((semiconductor or substrate or wafer) with ((ball or roller) ADJ3 (coat\$3 or plat\$3))) not solder) and (support with chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/13 14:22